IN THE CLAIMS

1-74. (canceled)

75. (currently amended) An electronic device, comprising:

a plurality of integrated circuit packages;

a contact surface electrically connected to a bottom edge of each integrated circuit package ~~of said packages~~; and

an integrated circuit package support comprising a first arm and a second arm each extending from the contact ~~said~~ surface at one end, and a base connecting the first arm and the second arm at opposite ends thereof, wherein the base of the support contacts only a center portion of a top edge of ~~and in contact with~~ each integrated circuit package~~, wherein the integrated circuit packages extend from the surface by a first distance and the support extends from the contact surface a second distance~~.

76.-79. (canceled)

80. (currently amended) The device of claim 75, wherein the ~~said~~ support comprises ~~is made of~~ a heat conducting material.

81. (currently amended) The device of claim 80, wherein the ~~said~~ material is a conformal material.

82. (currently amended) The device of claim 80, wherein the ~~said~~ material is a foam comprising ~~having~~ heat conductive particles ~~dispersed through it~~ to increase ~~its~~ heat conductivity.

83.-84. (canceled)

85. (currently amended) The device of claim 75~~claim 84~~, wherein ~~said support is made of plastic foam with~~ a plurality of

slots is formed in the base ~~therein~~, each slot being sized to resiliently engage one of the packages ~~said modules~~.

86.-87. (canceled)

88. (new) An electronic device, comprising:

a plurality of integrated circuit packages;

a contact surface electrically connected to a bottom portion of each package; and

an integrated circuit package support comprising a first portion and a second portion, wherein the first portion comprises two first arms each extending from the contact surface at one end and a first base connecting the two first arms at opposite ends thereof, wherein the second portion comprises two second arms each extending from the contact surface at one end and a second base connecting the two second arms at opposite ends thereof,

wherein a first edge of each integrated circuit package contacts the first base of the first portion and a second edge of each integrated circuit package contacts the second base of the second portion.

89. (new) The device of claim 88, wherein the support is resiliently biased against the first edge and the second edge of each integrated circuit.

90. (new) The device of claim 88, wherein the support comprises a heat conducting material.

91. (new) The device of claim 90, wherein the material is a conformal material.

92. (new) The device of claim 88, wherein the first base comprises first tabs and the second base comprises second tabs,

wherein the first tabs are arranged to engage first depressions formed in the first sides of the integrated circuit packages and the second tabs are arranged to engage second depressions formed in the second sides of the integrated circuit packages.